

# NORLAND

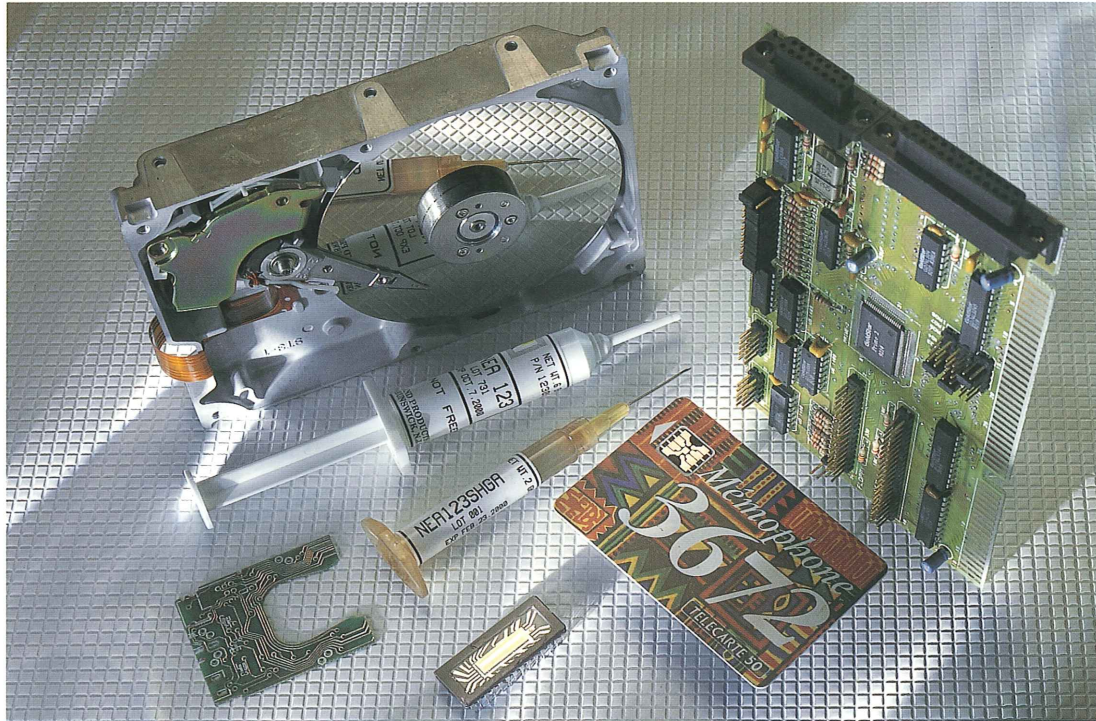
## Norland UV Curing Electronic Adhesives

**Norland Electronic Adhesives are designed for fast, precision bonding applications and will simplify processes that require critical alignment or exact positioning.**

*Used to manufacture electronic components including:*

- Head Gimbal Assemblies
- Circuit Boards
- Smart Cards
- EPROMs
- Optical Boards
- Flip Chips
- Optoelectronic Devices
- SMDs
- LCDs

to name a few...



### Norland Electronic Adhesives

These one part adhesives will set in seconds with UV light or cure with heat to form an electrically insulating bond to fasten, tack or fill. Areas not exposed to UV light can cure because of a latent heat catalyst.

### Norland Adhesives provide:

- Fast cure
- Long shelf life
- Strong bonds to glass, metal, ceramics and plastics
- Low shrinkage — low stress
- Gap filling properties

### Typical applications include:

- Coil Bonding
- Conformal Coating
- Encapsulating
- Fillet Bonding
- Fixturing
- Glob Top Assemblies
- Potting
- Sealing
- Screw Hole Sealing
- Strain Relief
- Tamperproofing
- Wire Tacking



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T E C H N I C A L D A T A

# Norland Electronic Adhesive (NEA)

Type	Description	Cure	ADHESION TO:			TYPICAL PROPERTIES					
			Glass	Metal	Plastic	Color	Viscosity at 25 Degrees C	Modulus PSI	Tensile PSI	Elongation at Failure	Shore D Hardness
NEA 121	Adhesive for tacking, filling, sealing, conformal coating and tamperproofing precision components.	UV/HEAT	Excellent	Excellent	Fair	Clear	300 CPS	160,000	3,500	30%	85
NEA 123	High viscosity thixotropic paste for wire tacking, chip bonding and coil terminating.	UV/HEAT	Excellent	Good	Good to Excellent	Translucent	200,000 CPS	50,000	3,000	60%	60
NEA 123L	Low viscosity thixotropic paste for sealing, chip bonding, filleting, wicking and thin sections.	UV/HEAT	Excellent	Good	Good to Excellent	Translucent	6,000 CPS	2,860	434	45%	67
NEA 123M	Low viscosity thixotropic paste for wire tacking, encapsulating, fixturing and tamperproofing.	UV/HEAT	Excellent	Good	Good to Excellent	Translucent	12,000 CPS	2,380	657	60%	64
NEA 123S	Medium viscosity thixotropic paste for sealing, wire coating, wire tacking and coil terminating.	UV/HEAT	Excellent	Good	Good to Excellent	Translucent	55,000 CPS	2,540	556	84%	75
NEA 123K	Medium viscosity thixotropic paste for glob top assemblies, potting, filling or thick sections.	UV/HEAT	Excellent	Good	Good to Excellent	Translucent	100,000 CPS	20,800	1,200	35%	67
NEA 123T	High viscosity thixotropic paste for wire encapsulating, coil terminating, screw hole sealing and potting.	UV/HEAT	Excellent	Good	Good to Excellent	Translucent	300,000 CPS	13,900	1,515	104%	55
NEA 123HGA	Low outgassing adhesive for HGA assembly or wire tacking.	UV/HEAT	Excellent	Good	Good to Excellent	Translucent	200,000 CPS	321,000	3,790	25%	60
NEA 123SHGA	Low outgassing, medium viscosity adhesive for wire coating, wire tacking and coil terminating.	UV/HEAT	Excellent	Good	Good to Excellent	Translucent	55,000 CPS	N/A	N/A	N/A	80
NCA 130	Electrically conductive adhesive for static dissipation.	UV/HEAT	Excellent	Good	Good to Excellent	Silver	10,000 CPS	N/A	N/A	N/A	15
<b>COLORED ADHESIVES:</b>											
NEA 123BL	High viscosity thixotropic paste for wire tacking, chip bonding or tamperproofing.	UV/HEAT	Excellent	Good	Good to Excellent	Blue	200,000 CPS	50,000	3,000	60%	60
NEA 123SBL	Medium viscosity thixotropic paste for tacking, sealing, filling or bonding precision components or wires in place.	UV/HEAT	Excellent	Good	Good to Excellent	Blue	55,000 CPS	2,540	556	84%	75
NEA 123R	High viscosity thixotropic paste for tacking, sealing, filling or bonding precision components or wires in place.	UV/HEAT	Excellent	Good	Good to Excellent	Red	200,000 CPS	50,000	3,000	60%	60
NEA 123GN	High viscosity thixotropic paste for tamperproofing, encapsulating, strain relief and wire tacking.	UV/HEAT	Excellent	Good	Good to Excellent	Green	200,000 CPS	50,000	3,000	60%	60
NEA 155	Medium/high viscosity thixotropic paste for SMDs, printed circuit boards, ceramics, metal and many plastics.	HEAT	Excellent	Good	Good to Excellent	Red	150,000 CPS	N/A	N/A	N/A	90

N/A — Not Available